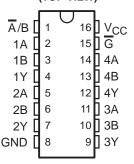
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- Controlled Baseline
 - One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of -40°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree[†]
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- Operates From 2 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 5.4 ns at 3.3 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2 V at V_{CC} = 3.3 V, T_A = 25°C

D OR PW PACKAGE (TOP VIEW)



description/ordering information

The SN74LVC157A-EP quadruple 2-line to 1-line data selector/multiplexer is designed for 2.7-V to 3.6-V V_{CC} operation.

This device features a common strobe (\overline{G}) input. When \overline{G} is high, all outputs are low. When \overline{G} is low, a 4-bit word is selected from one of two sources and is routed to the four outputs. The device provides true data.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

ORDERING INFORMATION

TA	T _A PACKAGE [‡]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC - D	Tape and reel	SN74LVC157AQDREP	C157AEP
	TSSOP - PW	Tape and reel	SN74LVC157AQPWREP	C157AEP

[‡] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

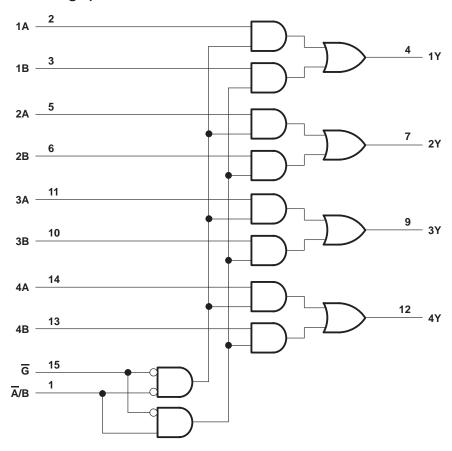
	INPUTS								
G	Ā/B	Υ							
Н	Χ	Χ	Х	L					
L	L	L	Χ	L					
L	L	Н	Χ	Н					
L	Н	Χ	L	L					
L	Н	Χ	Н	Н					



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}		0.5 V to 6.5 V
Input voltage range, VI (see Note	: 1)	0.5 V to 6.5 V
Output voltage range, VO (see No	otes 1 and 2)	\dots -0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} (V_{I} < 0)		–50 mA
Output clamp current, I _{OK} (V _O <	0)	–50 mA
Continuous output current, IO		±50 mA
Continuous current through V _{CC}	or GND	±100 mA
Package thermal impedance, θ, μ	(see Note 3): D package	
-	PW package	108°C/W
Storage temperature range, T _{sto}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The value of V_{CC} is provided in the recommended operating conditions table.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
.,	O mark worth and	Operating	2	3.6	
VCC	Supply voltage	Data retention only	1.5		V
VIH	High-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		V
VIL	Low-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		8.0	V
٧ _I	Input voltage		0	5.5	V
VO	Output voltage		0	VCC	V
	LPak book adout coment	$V_{CC} = 2.7 \text{ V}$		-12	4
ЮН	High-level output current	V _{CC} = 3 V		-24	mA
	Laveland autout aumant	$V_{CC} = 2.7 \text{ V}$		12	A
lOL	Low-level output current	V _{CC} = 3 V		24	mA
Δt/Δν	Input transition rise or fall rate			10	ns/V
T _A	Operating free-air temperature		-40	125	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARA	METER	TEST CONDITIONS	VCC	MIN	MAX	UNIT
		I _{OH} = -100 μA	2.7 V to 3.6 V	V _{CC} -0.2		
V		404	2.7 V	2.2		.,
VOH		$I_{OH} = -12 \text{ mA}$	3 V	2.4		V
		I _{OH} = -24 mA	3 V	2.2		
		$I_{OL} = 100 \mu\text{A}$	2.7 V to 3.6 V		0.2	
VOL		I _{OL} = 12 mA	2.7 V		0.4	V
		I _{OL} = 24 mA	3 V		0.55	
IĮ	All inputs	V _I = 5.5 V or GND	3.6 V		±5	μΑ
Icc		$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V		10	μΑ
ΔlCC		One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	2.7 V to 3.6 V		500	μΑ

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

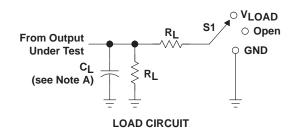
PARAMETER	FROM	TO	V _{CC} = 1	2.7 V	V _{CC} = ± 0.3	3.3 V 3 V	UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	
	A or B			6.2	0.8	5.4	
t _{pd}	Ā/B	Υ		8.2	0.8	7	ns
·	Io			7.8	0.8	6.5	

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST	V _{CC} = 2.5 V	V _{CC} = 3.3 V	LINUT
	FARAMETER	CONDITIONS	TYP	TYP	UNIT
C _{pd}	Power dissipation capacitance	f = 10 MHz	15	16	pF

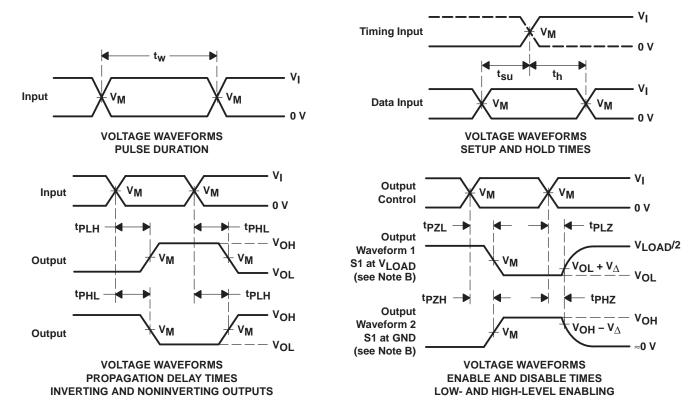


PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL tPLZ/tPZL	Open V _{LOAD}
tPHZ/tPZH	GND

	INF	PUTS	.,	.,	_	_	.,
VCC	V _I t _r /t _f		V _M	VLOAD	CL	RL	$v_{\scriptscriptstyle\Delta}$
2.7 V 3.3 V ± 0.3 V	2.7 V 2.7 V	≤2.5 ns ≤2.5 ns	1.5 V 1.5 V	6 V 6 V	50 pF 50 pF	500 Ω 500 Ω	0.3 V 0.3 V



- NOTES: A. C_I includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpzI and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ MSL rating/ Ball material Peak reflow		Op temp (°C)	Part marking
	(1)	(2)			(3)	(4)	(5)		(6)
SN74LVC157AQDREP	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C157AEP
SN74LVC157AQPWREP	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C157AEP
V62/04659-01XE	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C157AEP
V62/04659-01YE	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C157AEP

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



PACKAGE OPTION ADDENDUM

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● Catalog : SN74LVC157A

Automotive: SN74LVC157A-Q1

Military: SN54LVC157A

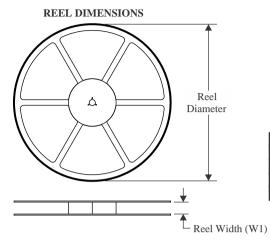
NOTE: Qualified Version Definitions:

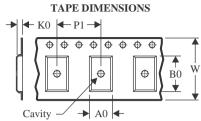
- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

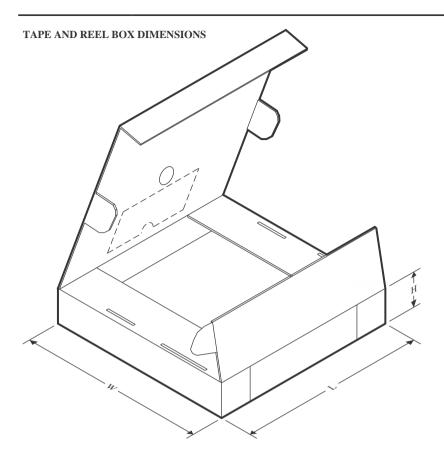
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC157AQDREP	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LVC157AQPWREP	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC157AQDREP	SOIC	D	16	2500	340.5	336.1	32.0
SN74LVC157AQPWREP	TSSOP	PW	16	2000	353.0	353.0	32.0

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